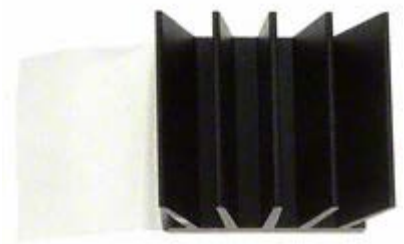


BGA Heat Sink - High Performance ASIC Cooling



ATS Part#: **ATS-56003-C1-R0**

Description: 15.00 x 15.00 x 9.00 mm BGA Heat Sink - High Performance ASIC Cooling

Heat Sink Type: ASIC Cooling

Heat Sink Attachment: Thermal Tape

Equivalent Part Number: **ATS-56003-C3-R0**

*Image above is for illustration purpose only.

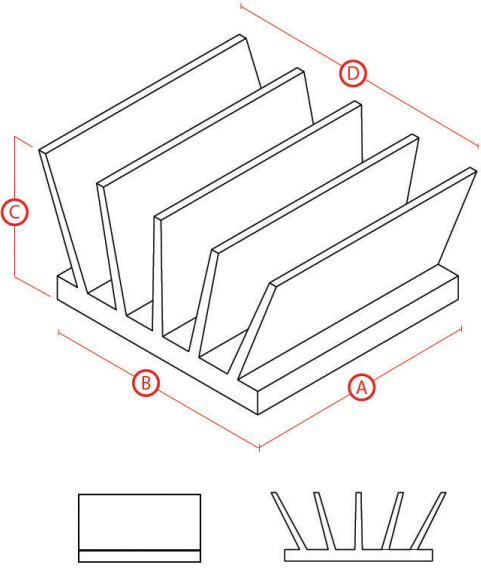
Features & Benefits

- **maxiFLOW™** design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- Designed specifically for ASIC package and their unique cooling requirements
- Comes preassembled with high performance thermal interface material

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	12 °C/W	10 °C/W	7.8 °C/W	6.9 °C/W	6 °C/W	5.7 °C/W	5.1 °C/W
	Ducted Flow	9	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish
	15.00 mm	15.00 mm	9.00 mm	17.8 mm	T412	BLACK-ANODIZED
Notes: • Dimension A and B refer to component size. • Dimension C is the heat sink height from the bottom of the base to the top of the fin field. • ATS-56003-C3-R0 is the exact heat sink assembly with an equivalent thermal interface material (Saint-Gobain C675). • Thermal performance data are provided for reference only. Actual performance may vary by application. • ATS reserves the right to update or change its products without notice to improve the design or performance. • ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant. • Contact ATS to learn about custom options available.						

*Image above is for illustration purpose only.